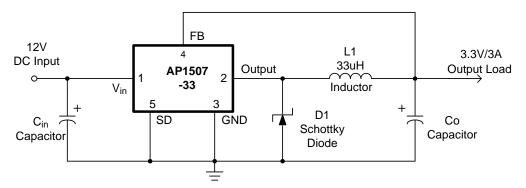
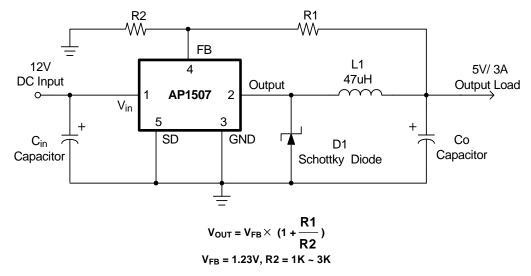


#### **Typical Application Circuit**

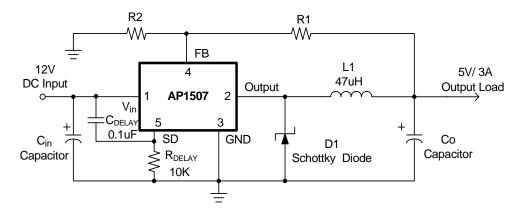
#### (1) Fixed Type Circuit



#### (2) Adjustable Type Circuit



(3) Delay Start Circuit

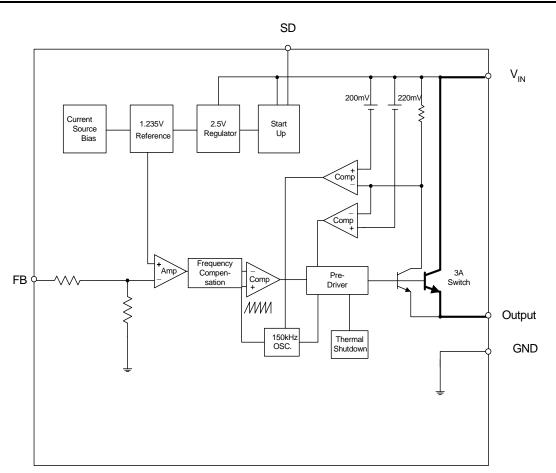




# **Pin Descriptions**

Pin Number	Pin Name	Description
1	VIN	Operating Voltage Input
2	Output	Switching Output
3	GND	Ground
4	FB	Output Voltage Feedback Control
5	SD	ON / OFF Shutdown

### **Functional Block Diagram**





### Absolute Maximum Ratings (T<sub>A</sub> = 25°C) (Note4)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage	+24	V
V <sub>SD</sub>	ON/OFF Pin Input Voltage	-0.3 to +18	V
V <sub>FB</sub>	Feedback Pin Voltage	-0.3 to +18	V
V <sub>OUT</sub>	Output Voltage to Ground	-1	V
PD	Power Dissipation	Internally Limited	W
T <sub>ST</sub>	Storage Temperature	-65 to +150	°C
TJ	Operating Junction Temperature	-40 to +125	°C

Note: 4. Stresses greater than the 'Absolute Maximum Ratings' specified above, may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.

# **Recommended Operating Conditions** (T<sub>A</sub> = 25°C)

Symbol	Parameter	Min	Мах	Unit
I <sub>OUT</sub>	Output Current	0	3	А
V <sub>OP</sub>	Operating Voltage	4.5	22	V
T <sub>A</sub>	Operating Ambient Temperature	-20	+85	°C



#### Electrical Characteristics (All Output Voltage Versions)

Unless otherwise specified,  $V_{IN} = 12V$  for 3.3V, 5V, adjustable version and  $V_{IN} = 18V$  for the 12V version.  $I_{LOAD} = 0.5A$ Specifications with **boldface type** are for full operating temperature range, the other type are for  $T_J = 25^{\circ}C$ .

Symbol	Paramete	er	Con	ditions	Min	Тур	Max	Unit		
I <sub>FB</sub>	Feedback Bias Curre	nt	V <sub>FB</sub> = 1.3V ( Adjustable Version Only )					-10	-50 <b>-100</b>	nA
_					127	150	173			
Fosc	Oscillator Frequency				110		173	KHz		
F <sub>SCP</sub>	Oscillator Frequency of Short Circuit Protect		When current V <sub>FB</sub> < 0.5V, T <sub>A</sub> =	limit Occurred and 25°C	10	30	50	KHz		
			I <sub>OUT</sub> = 3A				1.6			
V <sub>SAT</sub>	Saturation Voltage		No Outside Circuit V <sub>FB</sub> = 0V Force Driver On		1.4	1.4	1.7	V		
50	Max. Duty Cycle (ON)		V <sub>FB</sub> = 0V Force [	Driver On		100		0/		
DC	Min. Duty Cycle (OFF	-)	V <sub>FB</sub> = 12V Force	V <sub>FB</sub> = 12V Force Driver Off		0		%		
	I <sub>CL</sub> Current Limit		Peak Current				5.5	A		
ICL			No Outside Circuit V <sub>FB</sub> = 0V Force Driver On		3.6	4.5	6.5			
I <sub>LEAK</sub>	Output = 0V	Output leakage		No Outside Circuit V <sub>FB</sub> =12V Force Driver Off			-200	μA		
	Output = -1V	current	V <sub>IN</sub> = 22V			-5		mA		
lq	Quiescent Current		V <sub>FB</sub> = 12V Force	Driver Off		5	10	mA		
I <sub>STBY</sub>	Standby Quiescent Current		ON/OFF Pin = 5V V <sub>IN</sub> = 22V			70	150 <b>200</b>	μA		
V <sub>IL</sub>	ON/OFF Pin Logic In	out Threshold	Low (Regulator (	ON)	-		0.6			
VIH	Voltage		High (Regulator OFF)		2.0	1.3	-	V		
Ι <sub>Η</sub>	ON/OFF Pin Logic In	out Current	$V_{LOGIC} = 2.5V (OFF)$				-0.01			
١L	ON/OFF Pin Input Cu	irrent	$V_{LOGIC} = 0.5V (ON)$			-0.1	-1	μΑ		
θ <sub>JA</sub>	Thermal Resistance		TO252-5L	Junction to Case		10		°C/W		
θ <sub>JC</sub>	Thermal Resistance		TO252-5L Junction to Ambient			50		°C/W		



### Electrical Characteristics (All Output Voltage Versions)

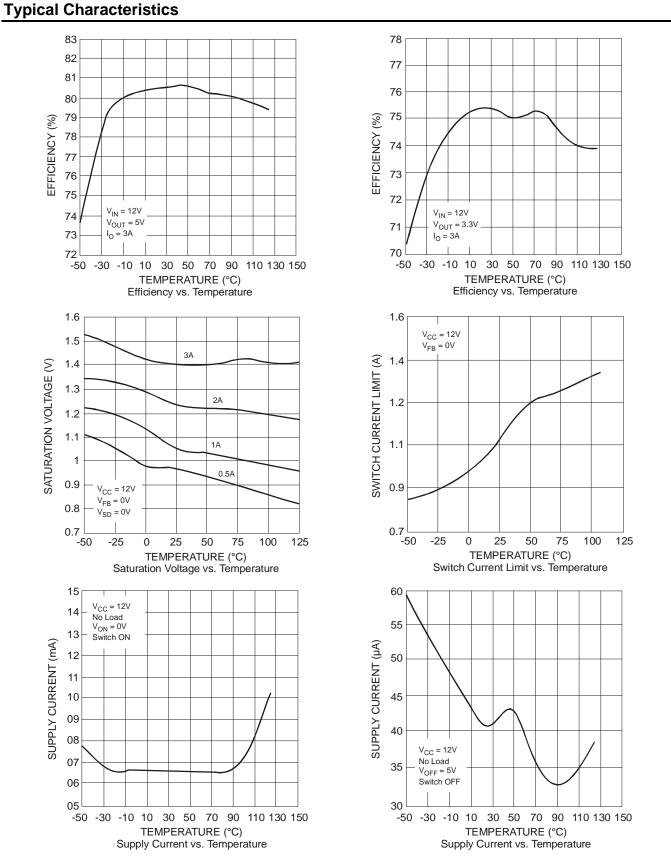
	Symbol	Parameter	Conditions	V <sub>MIN</sub>	Тур.	VMAX	Unit
AP1507-ADJ			5V <u>≤</u> V <sub>IN</sub> <u>≤</u> 22V 0.2A <u>≤</u> I <sub>LOAD</sub> <u>≤</u> 3A V <sub>OUT</sub> Programmed for 3V	1.193 <b>1.18</b>	1.23	1.267 <b>1.28</b>	V
	η	Efficiency	V <sub>IN</sub> = 12V, I <sub>LOAD</sub> = 3A		74		%
AP1507-3.3V	V <sub>OUT</sub>	Output Voltage	5.5V <u>≤</u> V <sub>IN</sub> <u>≤</u> 22V 0.2A <u>≤</u> I <sub>LOAD</sub> <u>≤</u> 3A	3.168 <b>3.135</b>	3.3	3.432 <b>3.465</b>	V
	η	Efficiency	V <sub>IN</sub> = 12V, I <sub>LOAD</sub> = 3A		75		%
AP1507-5V	Vout	Output Voltage	8V <u>&lt;</u> V <sub>IN ≤</sub> 22V 0.2A <u>&lt;</u> I <sub>LOAD</sub> <u>≤</u> 3A	4.8 <b>4.75</b>	5	5.2 <b>5.25</b>	V
	η	Efficiency	V <sub>IN</sub> = 12V, I <sub>LOAD</sub> = 3A		80		%
AP1507-12V	V <sub>OUT</sub>	Output Voltage	15V <u>≤</u> V <sub>IN</sub> <u>≤</u> 22V 0.2A <u>≤</u> I <sub>LOAD</sub> <u>≤</u> 3A	11.52 <b>11.4</b>	12	12.48 <b>12.6</b>	V
	η	Efficiency	V <sub>IN</sub> = 16V, I <sub>LOAD</sub> = 3A		89		%

Specifications with **boldface type** are for full operating temperature range, the other type are for  $T_J = 25^{\circ}C$ .



# AP1507

# 150KHz, 3A PWM BUCK DC/DC CONVERTER



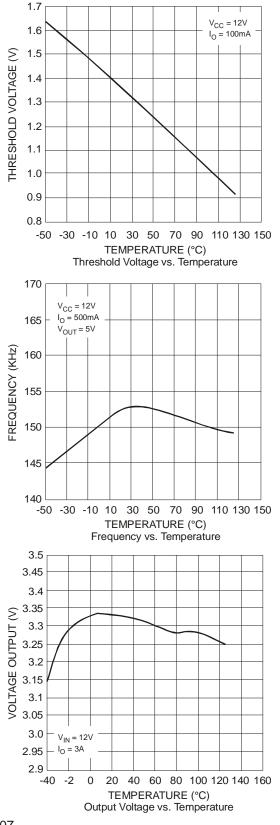
AP1507 Document number: DS31067 Rev. 3 - 2 Downloaded from Arrow.com.

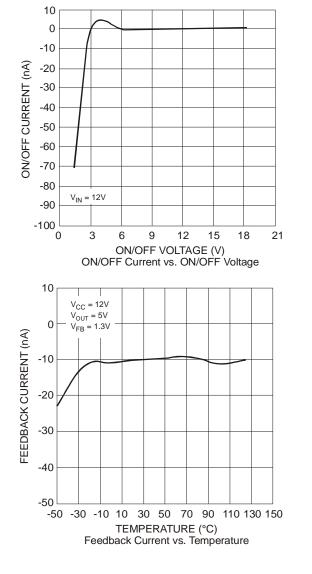


# AP1507

# 150KHz, 3A PWM BUCK DC/DC CONVERTER

### **Typical Characteristics (cont.)**







#### **Application Information**

#### **Pin Functions**

#### $+V_{IN}$

This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be present at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.

#### Ground

Circuit ground.

#### Output

Internal switch. The voltage at this pin switches between (+V<sub>IN</sub> - V<sub>SAT</sub>) and approximately - 0.5V, with a duty cycle of approximately V<sub>OUT</sub> / V<sub>IN</sub>. To minimize coupling to sensitive circuitry, the PC board copper area connected to this pin should be kept at a minimum.

#### Feedback (FB)

Senses the regulated output voltage to complete the feedback loop.

#### ON/OFF (SD)

Allows the switching regulator circuit to be shutdown using logic level signals thus dropping the total input supply current to approximately 150uA. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V (up to a maximum of 18V) shuts the regulator down. If this shutdown feature is not needed, the ON/OFF pin can be wired to the ground pin.

#### **Thermal Considerations**

The TO-252 surface mount package tab is designed to be soldered to the copper on a printed circuit board. The copper and the board are the heat sink for this package and the other heat producing components, such as the catch diode and inductor. The PC board copper area that the package is soldered to should be at least 0.8 in<sup>2</sup>, and ideally should have 2 or more square inches of 2 oz. additional copper areas which improves the thermal characteristics. With copper areas greater

than approximately 6in<sup>2</sup>, only small improvements in heat dissipation are realized. If further thermal improvements are needed, double sided, multi-layer PC board with large copper areas and/or airflow will be recommended.

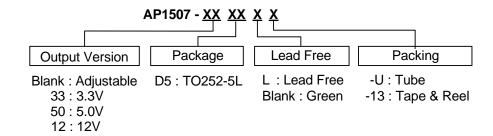
The AP1507 (TO-252 package) junction temperature rises above ambient temperature with a 3A load for various input and output voltages. This data was taken with the circuit operating as a buck-switching regulator with all components mounted on a PC board to simulate the junction temperature under actual operating conditions. This curve can be used for a quick check for the approximate junction temperature for various conditions, but there are many factors that can affect the junction temperature. When load currents higher than 3A are used, double sided or multi-layer PC boards with large copper areas and/or airflow might be needed, especially for high ambient temperatures and high output voltages.

For the best thermal performance, wide copper traces and generous amounts of printed circuit board copper should be used in the board layout. (One exception to this is the output (switch) pin, which should not have large areas of copper.) Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further.

Package thermal resistance and junction temperature rise numbers are all approximate, and there are many factors that will affect these numbers. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are trace width, total printed circuit copper area, copper thickness, single or double-sided, multilayer board and the amount of solder on the board. The effectiveness of the PC board to dissipate heat also depends on the size, quantity and spacing of other components on the board, as well as whether the surrounding air is still or moving. Furthermore, some of these components such as the catch diode will add heat to the PC board and the heat can vary as the input voltage changes. For the inductor, depending on the physical size, type of core material and the DC resistance, it could either act as a heat sink taking heat away from the board, or it could add heat to the board.



#### **Ordering Information**

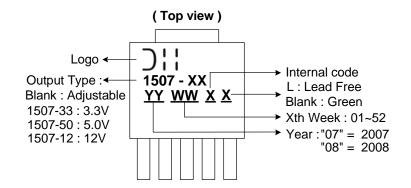


ſ			Deskering		e/Bulk	13" Tape an	d Reel
	Device	Package Code	Packaging (Note 5)	Quantity	Part Number Suffix	Quantity	Part Number Suffix
Pb Lead-Free	AP1507-XXD5L-XX	D5	TO252-5L	80	-U	2500/Tape & Reel	-13
Pop-	AP1507-XXD5-XX	D5	TO252-5L	Not available		2500/Tape & Reel	-13

Note: 5. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf

# **Marking Information**

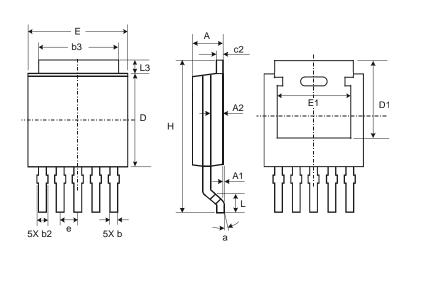
(1) TO252-5L





### Package Outline Dimensions (All Dimensions in mm)

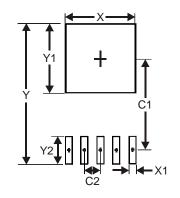
#### Package Type: TO252-5L



TO252-5L						
Dim	Min	Max	Тур			
Α	2.19	2.39	2.29			
A1	0.00	0.13	0.08			
A2	0.97	1.17	1.07			
b	0.51	0.71	0.583			
b2	0.61	0.79	0.70			
b3	5.21	5.46	5.33			
c2	0.45	0.58	0.531			
D	6.00	6.20	6.10			
D1	5.21	-	-			
е	-	-	1.27			
Е	6.45	6.70	6.58			
E1	4.32	-	-			
н	9.40	10.41	9.91			
L	1.40	1.78	1.59			
L3	0.88	1.27	1.08			
а	0°	10°	-			
All	All Dimensions in mm					

### **Suggested Pad Layout**

Package Type: TO252-5L



Dimensions	Value (in mm)
Х	5.6
X1	0.6
Y	11.0
Y1	5.6
Y2	2.0
C1	7.2
C2	1.27



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